TOHOKU UNIVERSITY SCIENCE SUMMER PROGRAM 2012

Merging Advanced Technology with Social Science

July 6th to July 13th 2012

About Tohoku University

Since its founding in 1907, Tohoku University has engaged in world-class education and research activities. Sendai city, where Tohoku University is located, has many cultural sites where you will have the chance to extensively experience Japanese culture.

TSSP 2012

The Tohoku University Summer Program in science and engineering has been conducted five times since 2007 with undergraduate students from all disciplines. Building on this experience and excellent results, this year we will offer the Tohoku University Science Summer Program (TSSP), which is customized specially for undergraduate students in science and engineering majors. We will offer classes in advanced sciences and engineering along with the social sciences in order to examine how Advanced Technologies can be applied to the Social Sciences.

Our aims are to provide students with insight on what world society needs in the future and how they can contribute to society through research. Students will choose 7 classes out of a selection of 9, allowing them to create a course of study suited to their own interests and academic goals.

The program is an 8-day summer program, which includes three components: lectures, laboratory visits, and fieldtrips. The following topics will be covered.

- Nano technology
- Bio technology
- Semiconductor
- Robotics
- Fuel Cell
- Artificial intelligence
- Agent-based models of society
- Game theory for economics
- Japanese architecture

*Topics are subject to change.

Application Procedures

To apply for this program, students must be nominated by their home institutions and submit all the documents through their home institutions. Prospective students need to submit the following documents via email.

1. Application Form for TSSP2012
2. ID Photo (4cm x 3cm) on the application form
3. Personal Statement (300-500 words)
4. Copy of your passport
Eligibility

Applicants must be undergraduate students in science/engineering majors enrolled in full time undergraduate degree programs at one of the following institutions. This program requires students to be fluent in English.

China
Tsinghua University
Zhejiang University
Fudan University
Tianjin University
Northeastern University

Germany
RWTH Aachen University

Denmark
Technical University of Denmark

Sweden
Uppsala University
KTH Royal Institute of Technology

Finland
Aalto University

France
Ecole Centrale de-Lyon
Université de Rennes 1

Australia
University of Sydney

United state of America
University of California Berkeley
University of California Davis
University of California San Diego
University of California Riverside
University of California Los Angeles
University of California Santa Barbara

Credits

Participating students are required to take at least 7 lectures, which is equal to 14 hours. On completing this requirement, the Tohoku University Summer Program (TSSP/TASP) should be eligible for *1 ECTS (European Credit Transfer System). These credits are not conferred at Tohoku University. Students who require credits for this program should inquire at their home universities.

*Note: ECTS credits are a value allocated to course units to describe the student workload required to complete them. In ECTS, 60 credits represent one year of study (in terms of workload)

Number of Seats

33 students

Location

Tohoku University, Sendai, JAPAN

Accommodation

Off-campus accommodation will be booked five-minutes by bus or twenty minutes' walk from Kawauchi campus, where most activities will be held during the program. A furnished individual bedroom with a unit bathroom costs 36,000yen (4,000yen per night) for your entire stay.

Application Deadline

April 20, 2012

Program Fee

Free (incl. Tuition and field trip)

Travel, accommodation, and everyday expenses should be paid individually. Students are advised to prepare sufficient money for food and personal expenses.

Scholarship (Students coming from China, Europe and the US)

JASSO scholarship, 80,000yen will be provided to students who successfully complete the program.